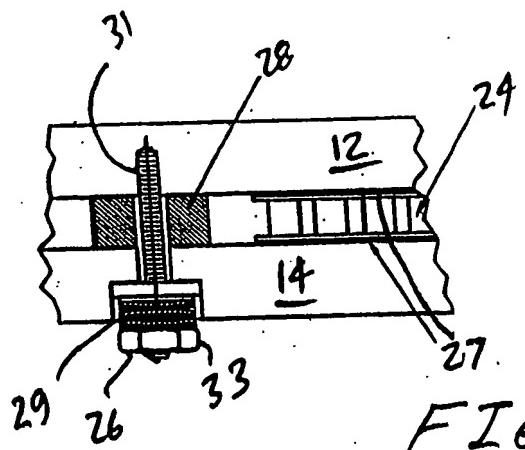
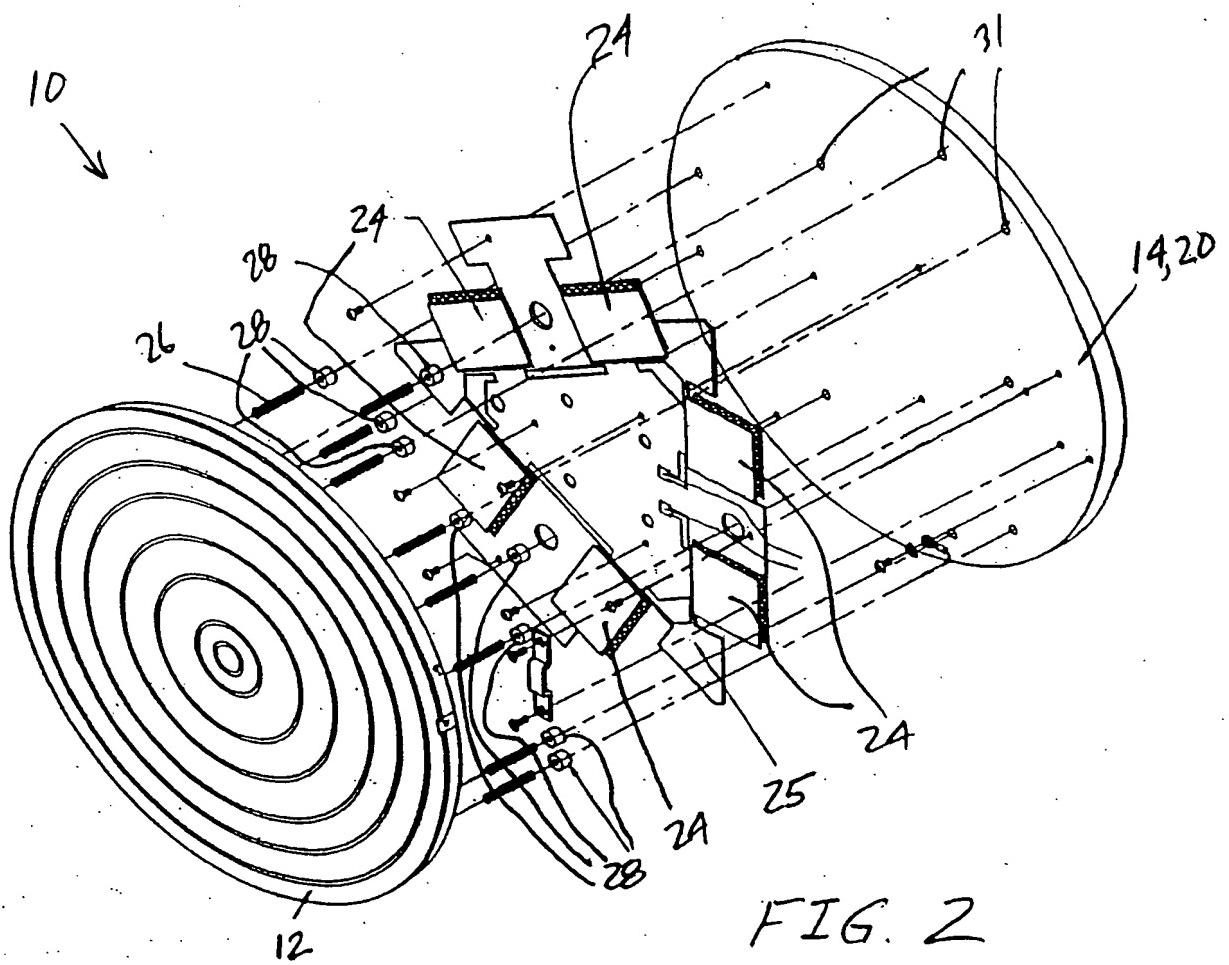
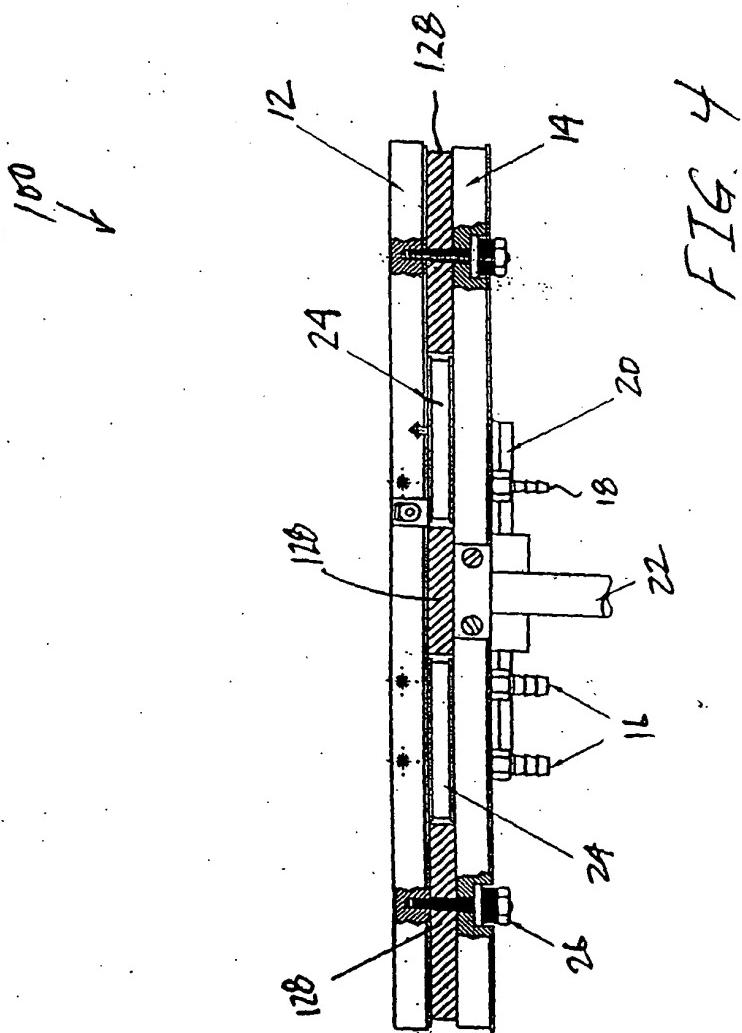


FIG. 1





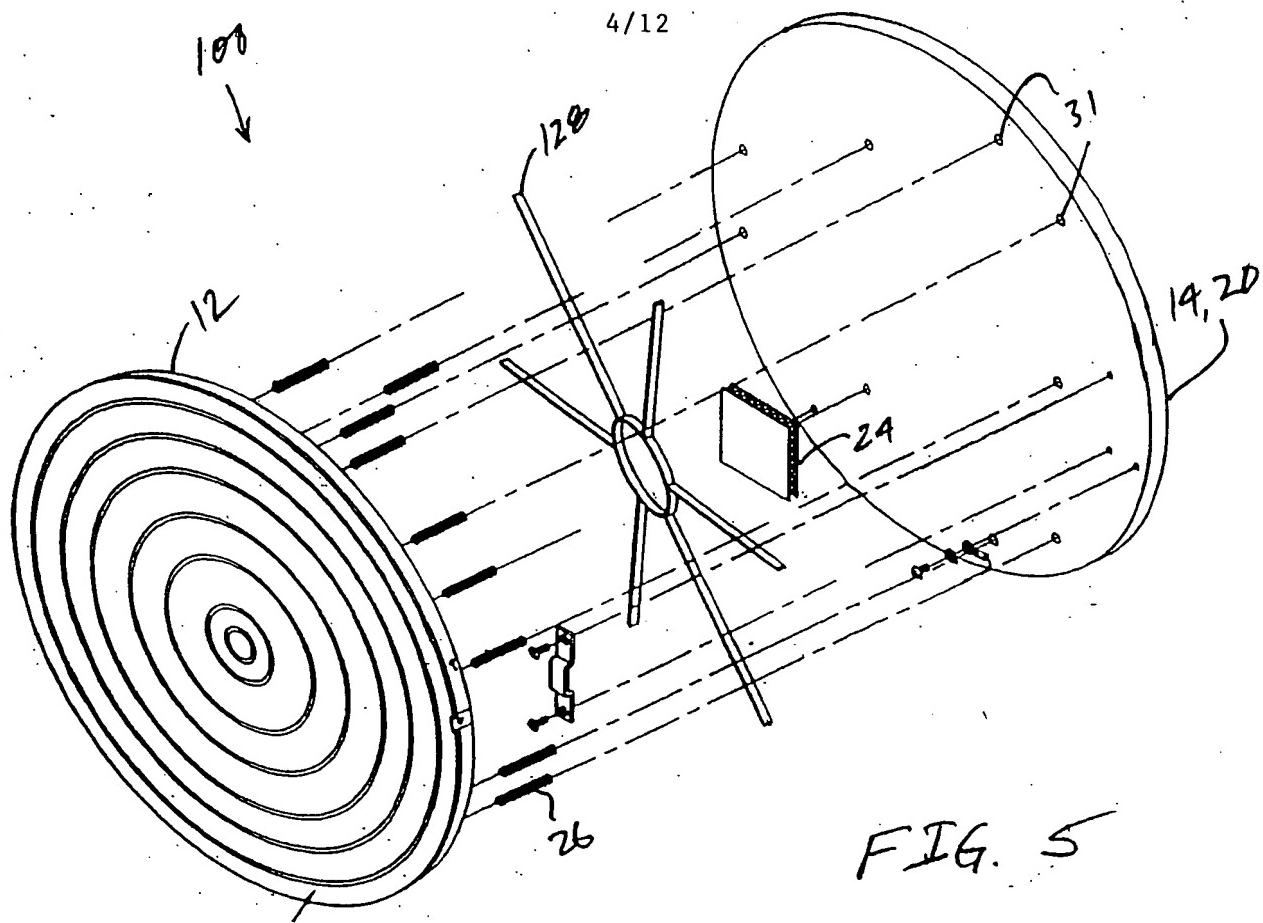


FIG. 5

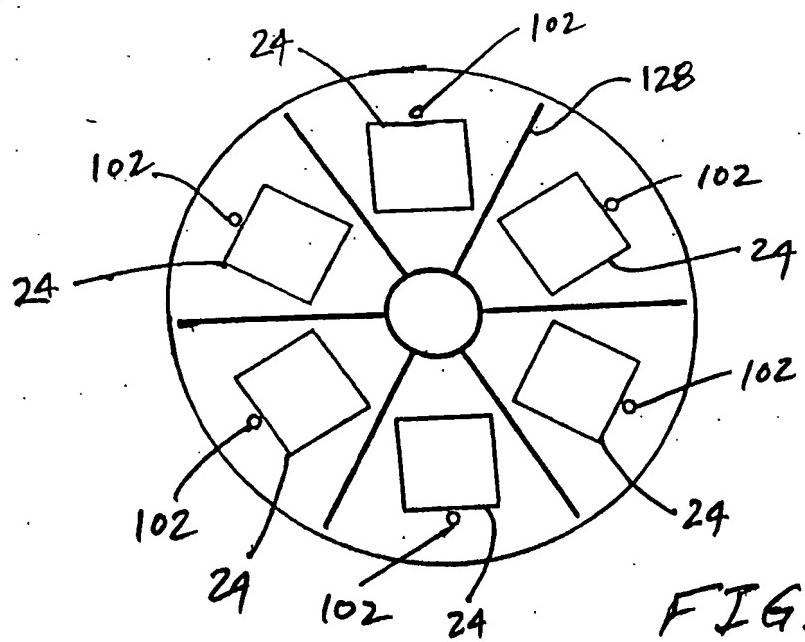


FIG. 6

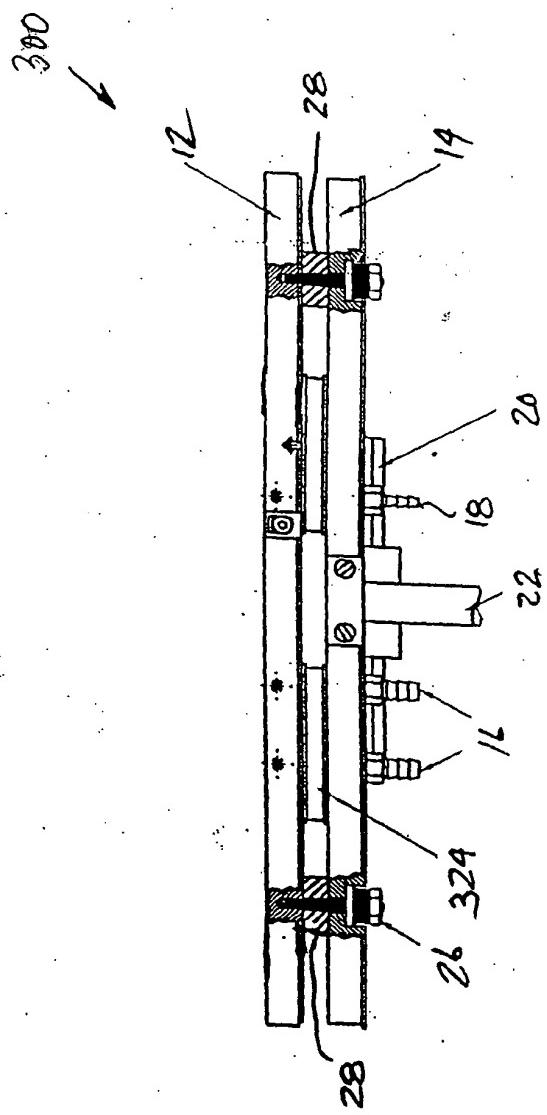


FIG. 7

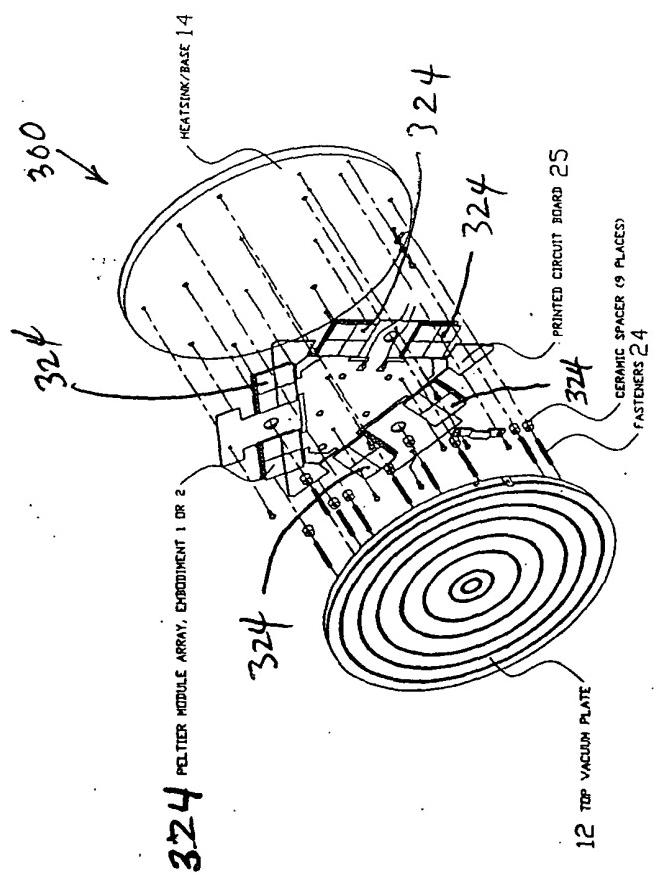
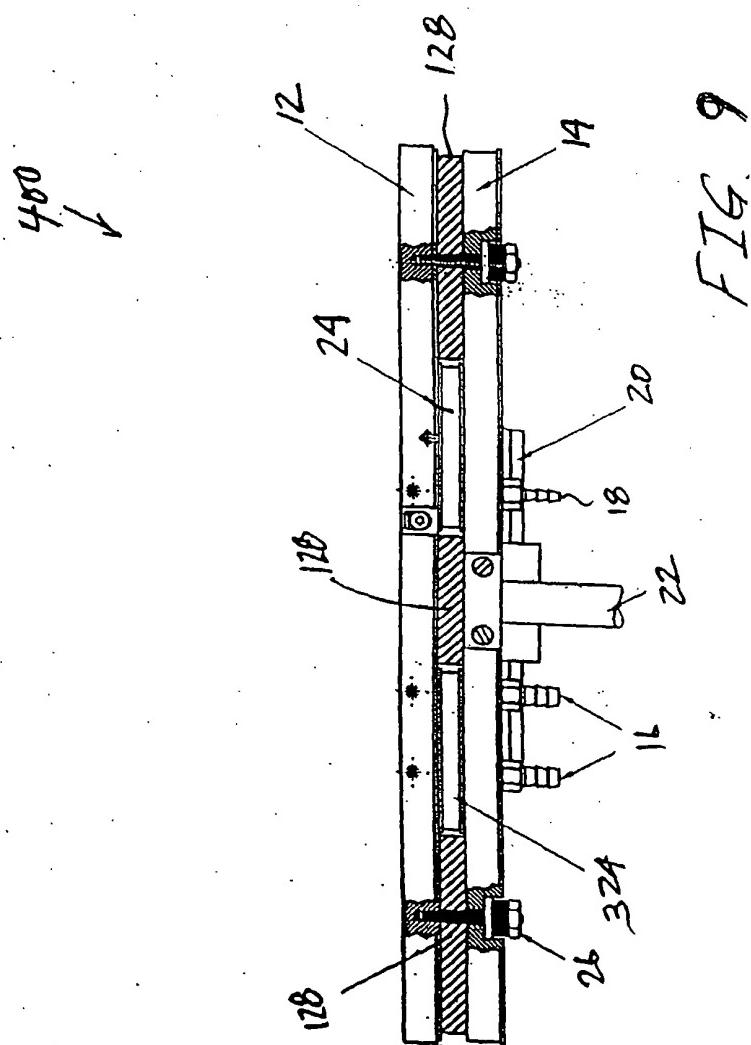
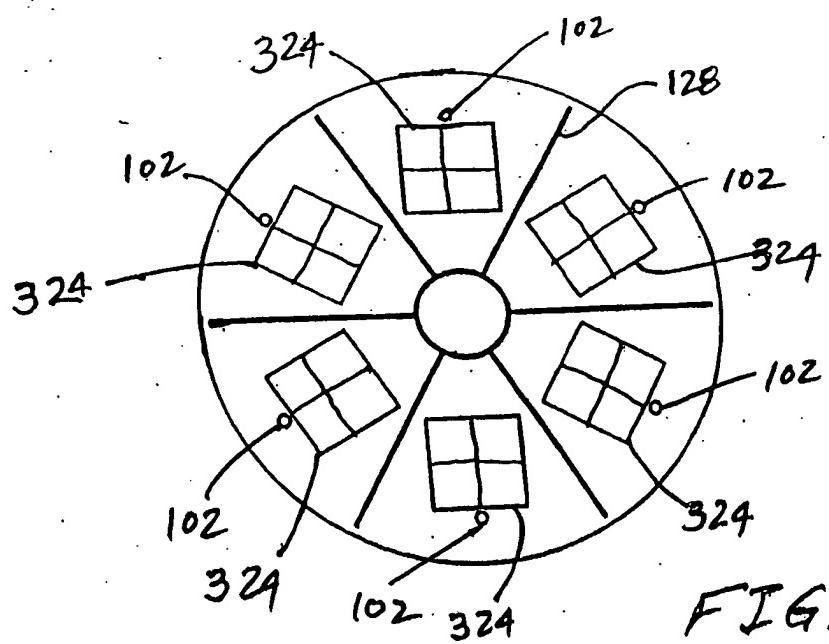
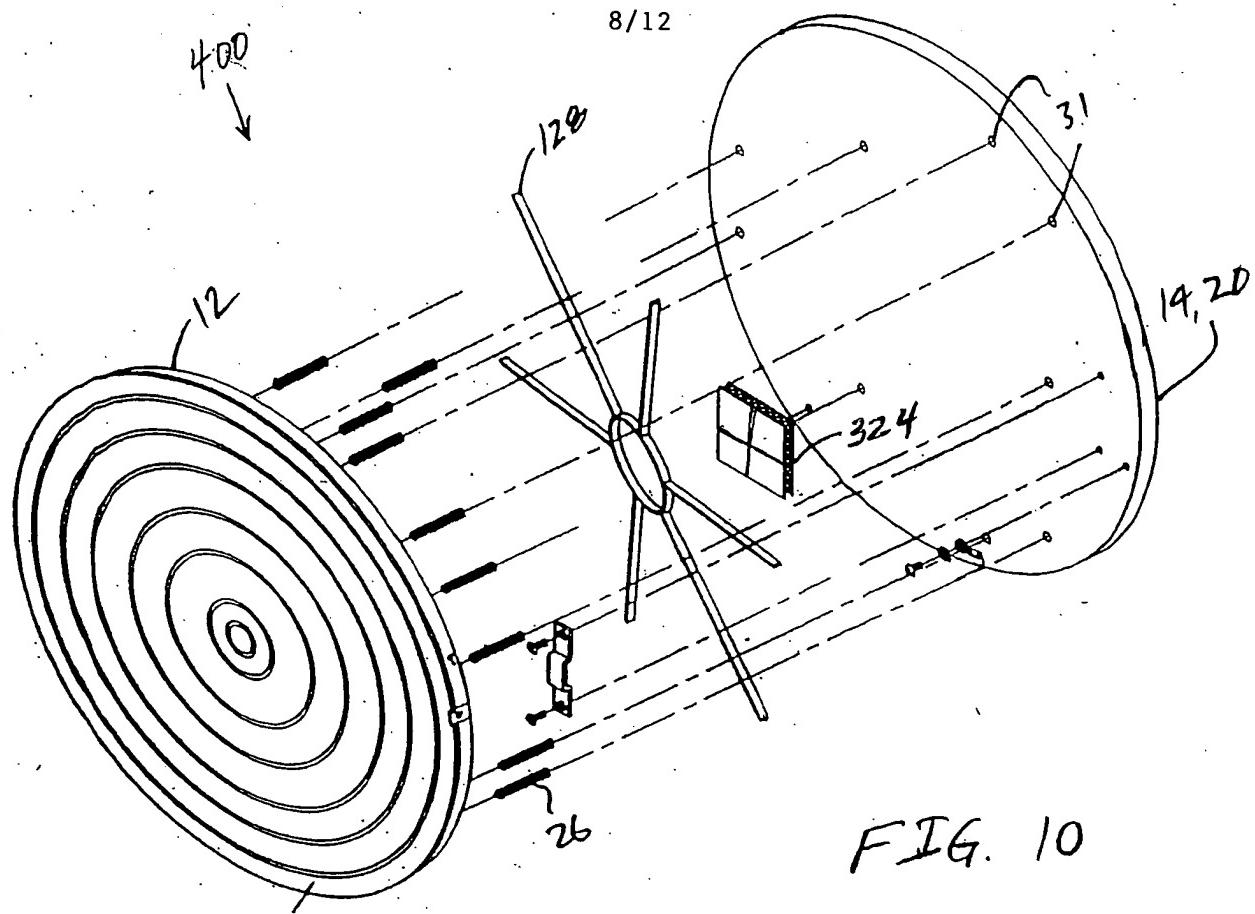
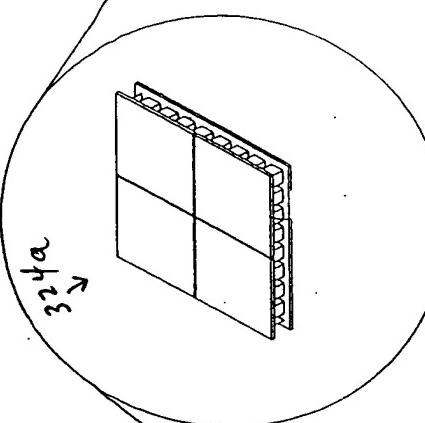


FIG. 8





EMBODIMENT 1
SINGLE, SILICONE
ELASTOMER SEALED
THERMOELECTRIC MODULE
WITH SEGMENTED 'HOT'
SIDE ONLY, ALLOWS
RELATIVE MOVEMENT OF
THE HOT SIDE DURING
TEMPERATURE TRANSITIONS



EMBODIMENT 2
MULTIPLE, SILICONE
ELASTOMER SEALED,
THERMOELECTRIC MODULES
ALLOWS RELATIVE
MOVEMENT BETWEEN THE
MODULES DURING
TEMPERATURE TRANSITIONS

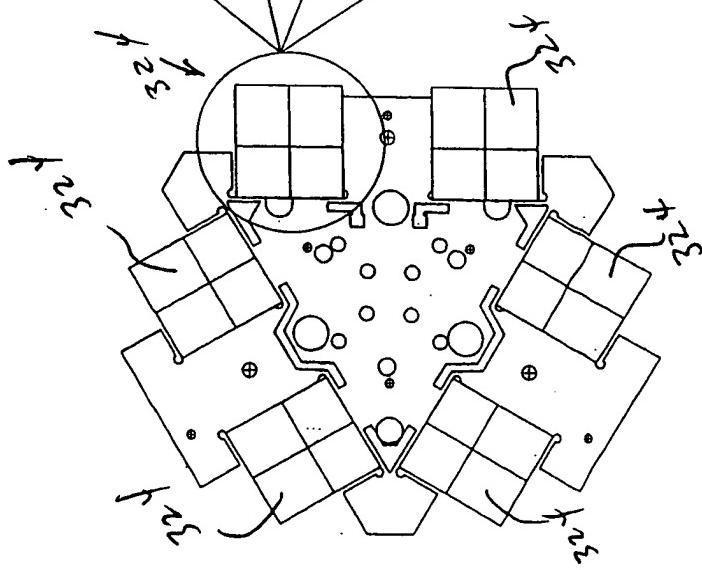
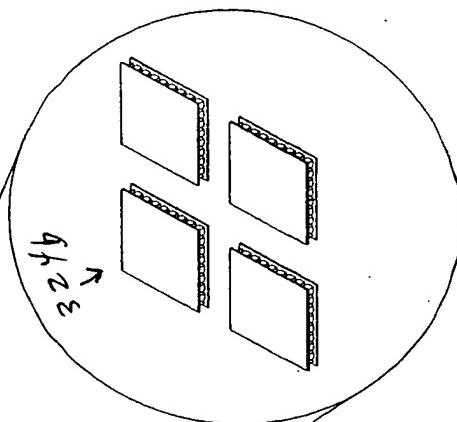
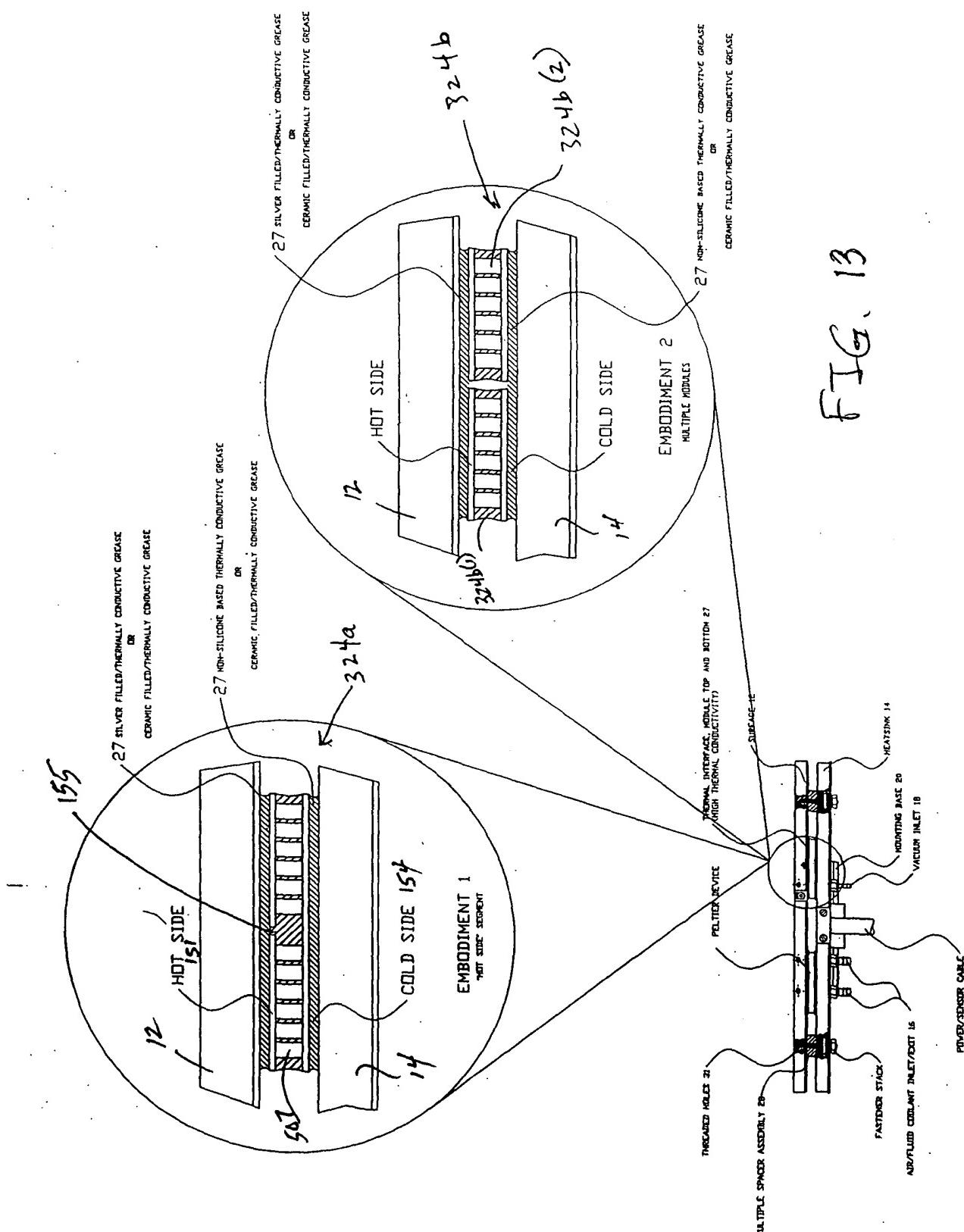
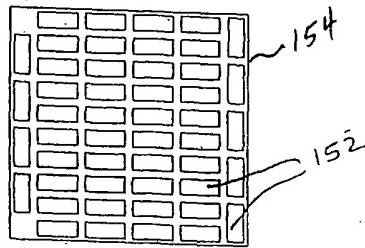
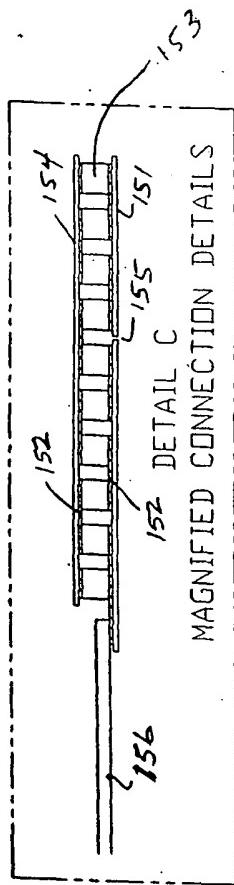


FIG. 12





VIEW B-B

COLD SIDE CERAMIC
SHOWING INTERNAL CONDUCTIVE
PAD CONNECTION LAYOUT

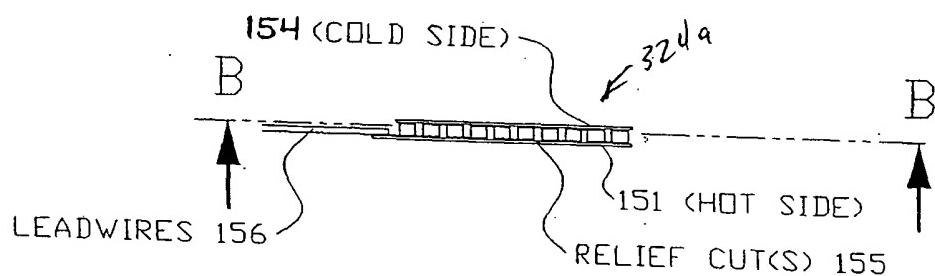


FIG. 14B

FIG. 14D

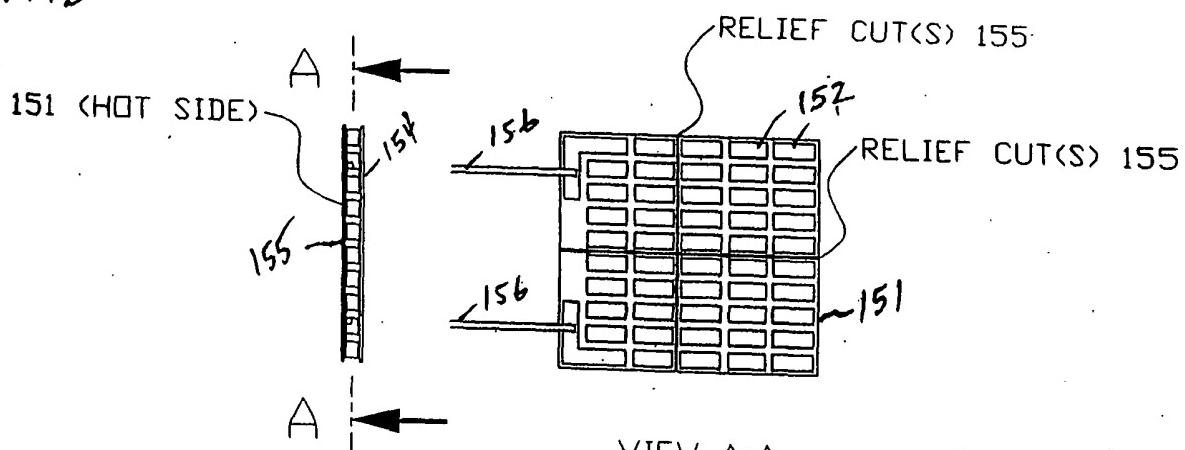


FIG. 14E

VIEW A-A
HOT SIDE CERAMIC
SHOWING INTERNAL CONDUCTIVE
PAD CONNECTION LAYOUT

FIG. 14C

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